Type-C Recepticle

Port select pin (SEL). Internally tied to GND via 100k resistor.
A: Port A to Port B
B: Port A to Port C

ESD Components
Please place UFP connector in pass-through position with no stub.

NOTE: ALL DIFF PAIRS ARE ROUTED 85 TO 90 OHMS DIFFERENTIAL AND 50 OHM COMMON MODE. ALL OTHER TRACES ARE 50 OHM.
The SATA TX differential pairs were swapped to simplify the EVM board layout. The TUSB9261 firmware provided by TI takes this swap into account.

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TPS65982 PD Controller

GPIO CONFIGURATION

GPIO0: 11900K [SuperSpeed USB Max Speed (Service Mode)]
GPIO1: Cable Pull-Down (up to 11900K)
GPIO2: Host Jack Detection [12V USB Input Detection]
GPIO3: Play Event [Cable Touch (Active High)]

Barrel Jack Detection [GPIO3]

S1_1A1 (GPIO15)
S1_3D1
Cable Attach (Active High) [GPIO1]
Plug Event [DEBUG1]

Barrel Jack Detection

NOTE: ALL DIFF PAIRS ARE ROUTED 85 TO 90 OHMS DIFFERENTIAL AND 50 OHM COMMON MODE. ALL OTHER TRACES ARE 50 OHM.

Note: If GPIOs are configured as "No Event Mapped" i.e. outputs, the 1MΩ pull-down resistors can be omitted.

Texas Instruments

TIDA-00882: USB Type-C HDD: TPS65982
5.25V (7A) Buck Converter

Input Range: 4.5 - 22V,
Auto-Skip Mode: 500kHz, 1.4ms soft start.

3.3V (300mA) LDO, 1.8V (300mA) LDO, and 1.1V (1A) Step-Down Converter

[Note: 1.8V is not utilized in this design]

Current Limiting Power Switch

Current Limit Threshold is 2.5 - 3.0A with 20K ILIM resistor

BARREL JACK DETECT

If DC_IN falls below 9V, comparator output will go low.
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